Texas Instruments

Bill of Materials

TI DESIGNS

TIDM-AIRQUALITYSENSOR

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Package
1	7	C1, C2, C3, C4, C14, C15, C16	0.1uF	0.1uF 16volts X7R 10%	Murata	GRM155R71C104KA88D	0402
2	2	C5, C7	12pF	12pF 25volts C0G 5%	Murata	GRM1555C1E120JA01D	0402
3	1	C6	220uF	16volts 220uF ESR 13mohm	Panasonic	16SEPC220MD	3.5mm
4	1	C8	0.47uF	0.47uF 10volts X5R 10%	Murata	GRM155R61A474KE15D	0402
5	1	C9	1.0uF	1.0uF 6.3volts X7R + - 10%	Murata	GRM155R70J105KA12D	0402
6	2	C10, C11	10uF	10uF 10volts X7R 10%	Murata	GCM21BR71A106KE22L	0805
7	2	C12, C17	0.1uF	10V 100nF 5%	Taiyo Yuden	LMK212SD104JG-T	0805
8	1	C13	0.001uF	0.001uF 10 volts 10%	Murata	GRM155R61A102KA01D	0402
9	3	C18, C19, C20	22uF	22uF 10% 16Volts	TDK Corporation	C2012X5R1C226K125AC	0805
10	1	D1	Red	Standard LEDs - Hyper Red	Lite-On	859-LTST-C170TBKT	0805
11	1	DEBUG_HEADER	1X04	4POS .100" STR TIN	Molex	901200124	1X04
12	1	DN7C3CA006_HEADER	JST-5-PTH	6 header connect for JST	JST	B6B-XH-A(LF)(SN)	JST-5-PTH
13	1	FAN_POWER	3.5MM-2	Screw Terminals 3.5mm Pitch	On Shore	OSTTE020104	3.5MM-2
14	2	J1, J2	1x10	10POS .100" STR TIN	Molex	901200130	1x10
15	1	JP2	2.1mm	CONN POWER JACK 2.1MM PC	Cui	PJ-202A	2.1mm
16	1	L1	1uH	FIXED IND 1UH 800MA	TDK Corporation	MLP2012S1R0T	2012
17	1	POWER_HEADER	1X02	2POS .100" STR TIN	Molex	901200122	1X02
18	3	R1, R4, R10	1MΩ	1M OHM 1%	Yageo	RC0805FR-071ML	0805
19	1	R2	150Ω	150 OHM 5%	Yageo	RC0805JR-07150RL	0805
20	1	R3	470Ω	470 OHM 1%	Yageo	RC0805FR-07470RL	0805
21	4	R5, R6, R7, R9	10MΩ	10K OHM 1%	Yageo	RC0402FR-0710KL	0402
22	1	R8	47KΩ	47K OHM 1%	Yageo	RC0402FR-0747KL	0402
23	1	S1	T062S	SWITCH TACTILE SPST-NO 0.05A 24V	Omron	B3S-1000P	T062S
24	1	TEST_HEADER	1X03	3POS .100" STR TIN	Molex	901200123	1X03
25	1	TPS63061	WSON10	2.5V to 12V Buck-Boost Converter	Texas Instruments	TPS63061DSCR	WSON10
26	1	VIM-878	VIM-878	LCD 14SEG 8DIG 0.275" TRANSF STD	Varitronix	VIM-878-DP-FC-S-LV	VIM-878
27	1	HDC1000	DSBGA8	Digital Humidity/Temp Sensor	Texas Instruments	HDC1000YPAT	DSBGA8
28	1	TPS715345	SC70-5L	50 mA, 24 V, 3.2-µA Iq, LDO	Texas Instruments	TPS715345DCKR	SC70-5L
29	1	MSP430	MSP430FR4133IPMR	16 MHz MCU 16 KB FRAM, 2 KB SRAM	Texas Instruments	MSP430FR4133IPMR	PM64
30	1	X1	32.768kHz	32.768kHz +/-20ppm 12.5pF -40C +85C	ABRACON	AB26TRQ-32.768kHz-T	NA
31	1	DN7C3CA006	Module	MOD PM2.5 DUST SENSOR	Sharp	DN7C3CA006	Module
32	2	U1, U2	BSN20-7	MOSFET NFET 30V .56A 1500M	ON Semiconductor	BSN20-7	SOT-23

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